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Advanced Electromagnetic Structures for Environmental Applications

Guest Editors:

Prof. Dr. Larbi Talbi

Department of Computer Science
and Engineering, University of
Quebec in Outaouais, Gatineau,
QC, Canada

Dr. Alireza Ghayekhloo

Department of Computer Science
and Engineering, University of
Quebec in Outaouais, Gatineau,
QC, Canada

Deadline for manuscript
submissions:

closed (31 July 2023)

Message from the Guest Editors

Among the most exciting topics of electromagnetic engineering are the studies of advanced electromagnetic (EM) structures. There are several venues to improve EM structure designs. Advanced electromagnetic structures (AES) such as metamaterials and metasurfaces can be applied to electronic applications related to the environment. Exploiting the Earth's resources to the fullest while considering green energy consumption is a current concern. Here, the AES proposes an effective way to interact with such a medium. Analytical solutions, simulation/numerical methods, and concrete experiments can all be used to characterize and assess the AES and its suggested application. The AES architectures that have been proposed would be used to support societal and industry-driven technologies.

The submission of high-quality research papers and review articles is encouraged for this issue. Designing EM propagating elements, communication links, and telecommunication circuits is the focus of this issue.



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Special Issue



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Editor-in-Chief

Prof. Dr. Sotirios K. Goudos

Department of Physics, Aristotle
University of Thessaloniki, 54124
Thessaloniki, Greece

Message from the Editor-in-Chief

I would like to introduce the new, online, and open access journal *Telecom*. The purpose of *Telecom* is to publish high-quality research papers as well as review articles that address recent advances in communications technology. We invite researchers to contribute original papers describing applications and experiences in emerging trends of all fields of telecommunications engineering. *Telecom* also welcomes Special Issue proposals from academics and industrial researchers. We aim to facilitate more collaboration between scientists and engineers around the world, such that they will produce their innovative ideas and submit their cutting-edge technologies to *Telecom*. We anticipate the receipt of your contributions to *Telecom*, and we welcome your comments and ideas on how to improve this journal.

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Telecom Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

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